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 Inputs Are TTL-Voltage Compatible Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption 	
Balanced Propagation Delays	
 ±24-mA Output Drive Current Fanout to 15 F Devices 	1B [] 3 14]] 4A 1Y [] 4 13]] 4B
 SCR-Latchup-Resistant CMOS Process and Circuit Design 	2A [] 5 12 [] 4Y 2B [] 6 11] 3A
 Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015 	2Y [7 10] 3B GND [8 9] 3Y

description/ordering information

This quadruple 2-line to 1-line data selector/multiplexer is designed for 4.5-V to 5.5-V V_{CC} operation.

The CD74ACT158 features a common strobe (\overline{G}) input. When the strobe is high, all outputs are high. When the strobe is low, a 4-bit word is selected from one of two sources and is routed to the four outputs. This device provides inverted data.

ORDERING INFORMATION

TA	PACKA	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–55°C to 125°C	SOIC – M	Tape and reel	CD74ACT158M96	ACT158M	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

(each data	aselect	or/multip	lexer)
	INPU	OUTPUT		
G	A/B	Α	В	Y
н	Х	Х	Х	Н
L	L	L	Х	Н
L	L	Н	Х	L
L	Н	Х	L	н
L	н	Х	Н	L

FUNCTION TABLE



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

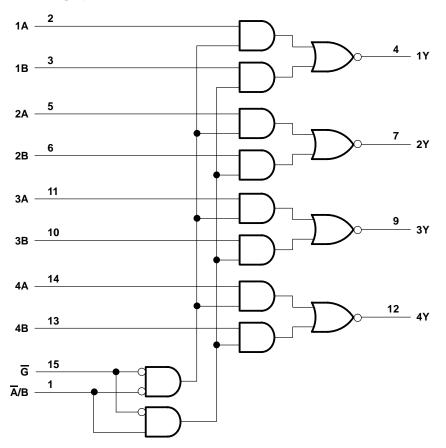
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, IIK (VI < 0 V or VI > VCC) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 V or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2)	73°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

		T _A = 2	T _A = 25°C		C to °C	–40° 85°		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-24		-24	mA
IOL	Low-level output current		24		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	DITIONS	vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT	
				MIN	MAX	MIN	MAX	MIN	MAX		
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4			
Vau	VI = VIH or VIL	I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8		V	
VOH	VI = VIH OL VIL	I _{OH} = -50 mA†	5.5 V			3.85				v	
		I _{OH} = -75 mA†	5.5 V					3.85			
	VI = VIH or VIL	I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1		
Ve		I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44	44 V	
VOL		I _{OL} = 50 mA [†]	5.5 V				1.65			v	
		I _{OL} = 75 mA [†]	5.5 V						1.65		
Ц	$V_I = V_{CC} \text{ or } GND$		5.5 V		±0.1		±1		±1	μA	
ICC	$V_I = V_{CC} \text{ or } GND,$	IO = 0	5.5 V		8		160		80	μA	
ΔI_{CC}^{\ddagger}	$V_{I} = V_{CC} - 2.1 V$		4.5 V to 5.5 V		2.4		3		2.8	mA	
Ci					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.
 [‡] Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A or B	0.37
G	0.83
Ā/B	1.33

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).



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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

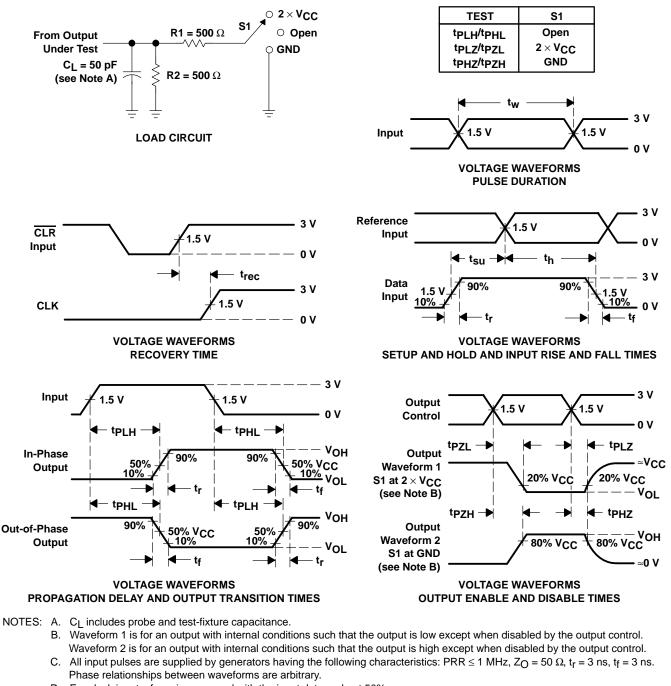
PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55° 125		–40°(85°	UNIT	
			MIN	MAX	MIN	MAX	
^t PLH	A or B	Any Y	2.3	9.2	2.4	8.4	
^t PHL	AUB	Ally I	2.3	9.2	2.4	8.4	ns
^t PLH	Ā/B	Any Y	3.4	13.5	3.6	12.3	ns
^t PHL	А/В		3.4	13.5	3.6	12.3	115
^t PLH	G	Any Y	3.1	12.4	3.3	11.3	200
^t PHL	9		3.1	12.4	3.3	11.3	ns

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	149	pF

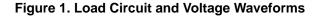


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PARAMETER MEASUREMENT INFORMATION

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tp71 and tp7H are the same as ten.
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- I. All parameters and waveforms are not applicable to all devices.







10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD74ACT158M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT158M	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

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⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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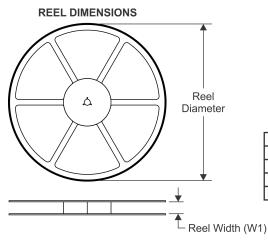
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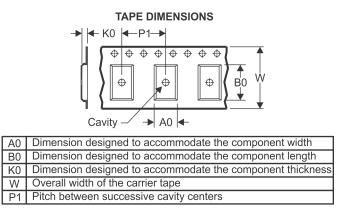
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing	Pins		Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT158M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

27-Jul-2021



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT158M96	SOIC	D	16	2500	340.5	336.1	32.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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